

MEG-02-006017



May 24, 2007

To: Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject:

Serial No.	10/786,807	02/25/2004
H. M. CHEN		
"METHOD FOR IMPROVING SEMICONDUCTOR WAFER TEST ACCURACY"		
Grp. Art Unit: 2822	AU, BACH	

#### RESPONSE TO NON-FINAL OFFICE ACTION

Dear Sir:

In response to the Non-Final Office Action mailed Mar. 21, 2007, please amend the above-identified application for patent and consider the remarks, as follows:

#### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on Jun. 21, 2007.

Stephen B. Ackerman, Reg. No. 37,761

Signature

Date 6/21/07

Amendments to the Claims are reflected in the listing of the Claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 5 of this paper.